# **RX** Capacitive Touch Evaluation System

Self-Capacitance Touch Buttons/Wheels/Slider Board

User's Manual

Renesas Solution Starter Kit RX Capacitive Touch Evaluation System Application Board

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## General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

#### 1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

#### 2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power is supplied until the power reaches the level at which reseting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

#### 5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a systemevaluation test for the given product.

## How to Use This Manual

### 1. Purpose and Target Readers

This manual is designed to provide the user with a general understanding of the Capacitive Touch Application Board and its electrical characteristics. It is intended for users designing sample code on the RSSK platform, using the many different incorporated peripheral devices.

The manual includes an overview of the Capacitive Touch Application Board functions, but does not serve as a guide for embedded programming or hardware design. A basic knowledge of electric circuits, logical circuits, and MCUs is necessary in order to use this manual.

Particular attention should be paid to the precautionary notes when using the manual. These notes occur within the body of the text, at the end of each section, and in the Usage Notes section.

The revision history summarizes the locations of revisions and additions. It does not list all revisions. Refer to the text of the manual for details.

The following documents apply to the Capacitive Touch Application Board included in the Renesas Capacitive Touch Evaluation System. Make sure to refer to the latest versions of these documents. The newest versions of the documents listed may be obtained from the Renesas Electronics Web site.

| Document Type | Description  | Document Title   | Document No.       |  |  |
|---------------|--|--|--------------------|--|--|
| User's manual | Description of application board hardware specifications | RX Capacitive Touch<br>Evaluation System: Self-<br>Capacitance<br>Buttons/Wheels/Slider<br>Board User's Manual | This User's Manual |  |  |

## 2. List of Abbreviations and Acronyms

| Abbreviation | Full Form                                     |
|--------------|---|
| ACIA         | Asynchronous Communications Interface Adapter |
| bps          | bits per second                               |
| CRC          | Cyclic Redundancy Check                       |
| DMA          | Direct Memory Access                          |
| DMAC         | Direct Memory Access Controller               |
| GSM          | Global System for Mobile Communications       |
| Hi-Z         | High Impedance                                |
| IEBus        | Inter Equipment Bus                           |
| I/O          | Input/Output                                  |
| IrDA         | Infrared Data Association                     |
| LSB          | Least Significant Bit                         |
| MSB          | Most Significant Bit                          |
| NC           | Non-Connect                                   |
| PLL          | Phase Locked Loop                             |
| PWM          | Pulse Width Modulation                        |
| SFR          | Special Function Register                     |
| SIM          | Subscriber Identity Module                    |
| UART         | Universal Asynchronous Receiver/Transmitter   |
| VCO          | Voltage Controlled Oscillator                 |

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#### Precautions

This Evaluation Kit is only intended for use in a laboratory environment under ambient temperature and humidity conditions. A safe separation distance should be used between this and any sensitive equipment. Its use outside the laboratory, classroom, study area, or similar such area invalidates conformity with the protection requirements of the Electromagnetic Compatibility Directive and could lead to prosecution.

The product generates, uses, and can radiate radio frequency energy and may cause harmful interference to radio communications. There is no guarantee that interference will not occur in a particular installation. If this equipment causes harmful interference to radio or television reception, which can be determined by turning the equipment off or on, you are encouraged to try to correct the interference by one or more of the following measures:

• Ensure attached cables do not lie across the equipment.

- · Reorient the receiving antenna.
- Increase the distance between the equipment and the receiver.
- · Connect the equipment into an outlet on a circuit different from that which the receiver is connected.
- · Power down the equipment when not in use.
- · Consult the dealer or an experienced radio/TV technician for help.

Note: It is recommended that wherever possible shielded interface cables are used.

The product is potentially susceptible to certain EMC phenomena. To mitigate against them it is recommended that the following measures be undertaken:

- The user is advised that mobile phones should not be used within 10 m of the product when in use.
- . The user is advised to take ESD precautions when handling the equipment.

The Evaluation Kit does not represent an ideal reference design for an end product and does not fulfill the regulatory standards for an end product.

## Safety Items

## **Definitions of Symbols**

A variety of symbols are used in this document and on the product itself to prevent in advance danger to you the user or any third parties and to prevent in advance damage to any physical property. This section, Safety Items, presents these symbols and their meanings. It also presents safety notes to assure that this produce is used safely and correctly.

This product should only be used after fully understanding the material presented in this section.



Warning items indicate things that, if not avoided, could lead to death or serious injury.



Caution items indicate both latent dangers that can lead to minor or moderately severe injury and latent dangers that can lead to property damage if not avoided.

In addition to the above two markings, the following are displayed at the same time if appropriate.

**[Important]** Indicates a point that can lead to equipment failure or malfunction if incorrectly set when setting up this product.

A triangular mark riangle indicates a warning or caution.

Example:



The



### Warning

# Marning

Handling related warnings:

Do not disassemble or modify this product. Renesas does not guarantee this product if it has been disassembled or modified.

The power supply for this product can be selected to be either the USB bus or a DC jack. A jumper is used to select the power supply.

If, during either use or storage of this product, any abnormality in the product itself (including abnormal odors, heating, color changes, or shape changes to the product itself) are observed, disconnect the USB cable and power supply cable immediately.

#### Installation:



Do not install this equipment in a location that has a high humidity or where water or other fluids could get on it. This equipment may be damaged if water or other fluids could get on it.

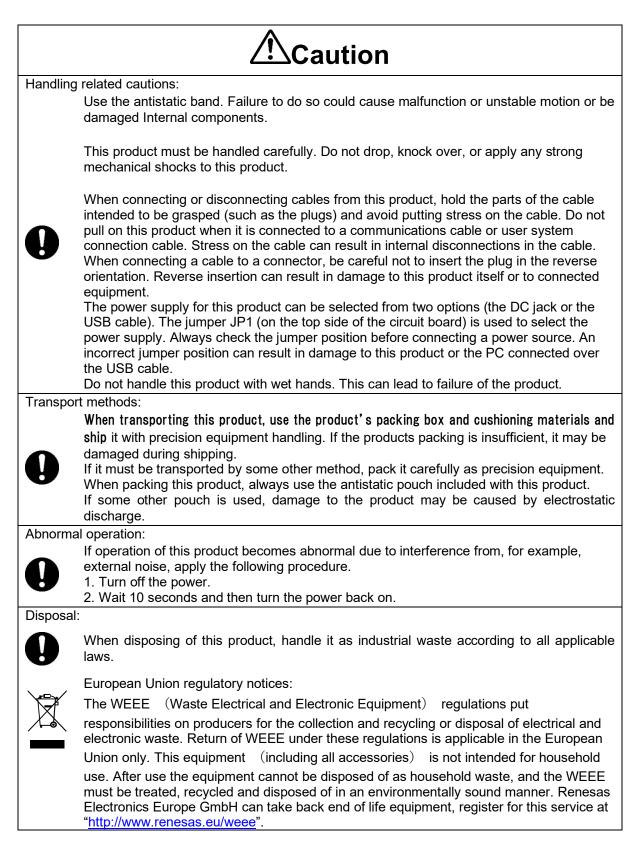
#### Ambient temperature:

0

The upper limit for the ambient temperature under which this product may be used is  $35^{\circ}$ C.

This maximum rated ambient temperature must not be exceeded.

## Caution



## Electromagnetic Environment

# Electromagnetic Environment



This product generates electromagnetic emissions in an industrial environment. Use in a residential environment may affect other equipment.
 This product requires special EMC precoutions and should be used in accordance with the EMC.

This product requires special EMC precautions and should be used in accordance with the EMC information provided below.

| EMI: Electro Magnetic Interference |               |                |   |  |  |  |  |
|------------------------------------|---------------|----------------|---|--|--|--|--|
| Stan                               | dard          | Level          | Guidance for EMC protection   |  |  |  |  |
| Test Item                          | EN 55011      | Group1 Class A | This product has no intentional<br>external emissions, but internal<br>RF emissions may affect nearby |  |  |  |  |
| Radiated Emissions                 | :2009+A1:2010 |                | electronic equipment.   |  |  |  |  |

| EMS: Electro Magnetic Susceptibility     |                                       |                 |  |  |  |  |  |
|--|---------------------------------------|-----------------|--|--|--|--|--|
| Stan                                     | dard                                  | Level           | Guidance for EMC protection  |  |  |  |  |
| Electrostatic<br>Discharge               | EN 61000-4-2:2009                     | B <sup>*1</sup> | This product is intended for use in<br>electromagnetic environments in<br>industrial settings. The user of the<br>product should pay particular attention to<br>the following electromagnetic immunity.  |  |  |  |  |
| Radio Frequency<br>Electromagnetic Field | EN 61000-4-3:<br>2006+A1:2008+A2:2010 | A*2             | <ul> <li>Power supply quality</li> <li>Protection against static electricity</li> <li>Protection against external high-power radio waves</li> <li>Protection against external magnetic fields</li> </ul> |  |  |  |  |

## \*1 Test Condition of Electrostatic Discharge

| Discharg           | e Method          | Test Voltage | Result |
|--------------------|-------------------|--------------|--------|
| Indirect Discharge | VCP               | ±4.0kV       | Pass   |
|                    | HCP               | ±4.0kV       | Pass   |
|                    | Contact Discharge | ±4.0kV       | Pass   |
| Direct Discharge   |                   | ±2.0kV       | Pass   |
| Direct Discharge   | Air Discharge     | ±4.0kV       | Pass   |
|                    | -                 | ±8.0kV       | Pass   |

\*2 Test Condition of Radio Frequency Electromagnetic Field

| Test Level             | Dwell Time | Modulation | Frequency<br>Step | Antenna<br>Polarization | Result |
|------------------------|------------|------------|-------------------|-------------------------|--------|
| 3V/m (80MHz - 1.0GHz)  | 1.0sec     | 1kHz       | 1.0%              | Horizontal              | Pass   |
| 3V/m (1.4GHz – 6.0GHz) | 1.0000     | AM 80%     | 1.070             | / Vertical              | Pass   |

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## RENESAS

Self-Capacitance Touch Buttons/Wheels/Slider Board RX Capacitive Touch Evaluation System Application Board

## 1. Overview

## 1.1 Purpose

This product was developed for use with a CPU board as an evaluation tool for the Renesas RX Capacitive Touch Evaluation System.

## 1.2 Features

This application board offers the following features:

- Connectable to the CPU board included in the Renesas RX Capacitive Touch Evaluation System
- Same interface as the CPU board included in Renesas RX Capacitive Touch Evaluation System
- Button/wheel/slider board
  - 3 self-capacitance button electrodes
  - 2 types of wheel electrodes (8-electrode and 4-electrode)
  - 1 slider electrode (5 electrodes)
- 3-mm thick acrylic overlay (attached)
- Dimensions (L x W x H) : 145mm x 151mm x 12mm



#### Figure 1.1 Application Board External Dimensions



## 1.3 Regulatory Compliance Notices

#### 1.3.1 European Union regulatory notices

This product complies with the following EU Directives. (These directives are only valid in the European Union.)

#### CE Certifications:

## Electromagnetic Compatibility (EMC) Directive 2014/30/EU EN IEC 61326-1: 2021 Group1 Class A

| WARNING: | This is a Class A product. This equipment can cause radio frequency noise when used in the  |
|----------|---|
|          | residential area. In such cases, the user/operator of the equipment may be required to take |
|          | appropriate countermeasures under his responsibility.                                       |

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  - Name: Renesas Electronics Corporation
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- · Person responsible for placing on the market
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  - Address: Arcadiastrasse 10, 40472 Dusseldorf, Germany
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  - Product name: RX130 Capacitive Touch Evaluation System
  - Type name: RTK0EG0003S02001BJ

Environmental Compliance and Certifications:

Waste Electrical and Electronic Equipment (WEEE) Directive 2012/19/EU



## 2. Board Layout

## 2.1 Component Layout

Figure 2.1 shows the component layout of the application board.

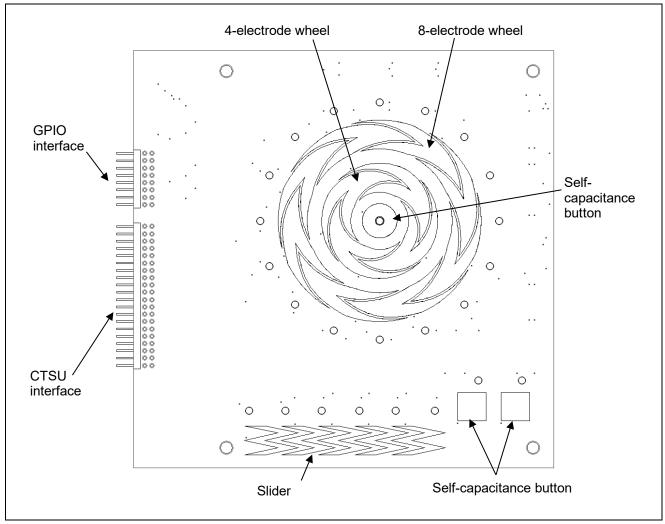


Figure 2.1 Component Layout



## 2.2 Overlay Dimensions

Figure 2.2 shows the dimensions of the overlay attached to the application board. Dimensions are shown in millimeters. Overlay thickness is 3.0 mm.

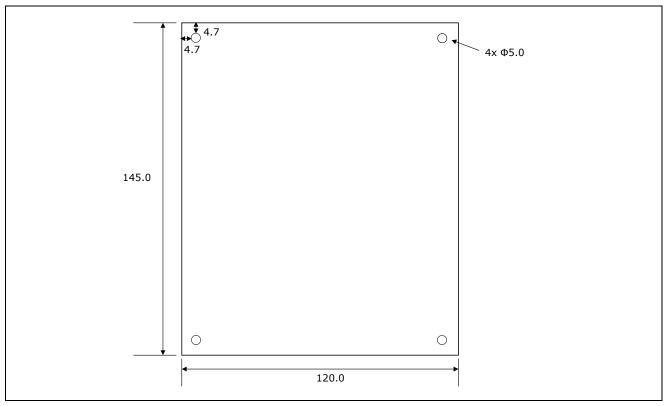


Figure 2.2 Overlay Dimensions



### 2.3 Component Placement

Figures 2.3 and 2.4 show the placement of individual components on the application board.

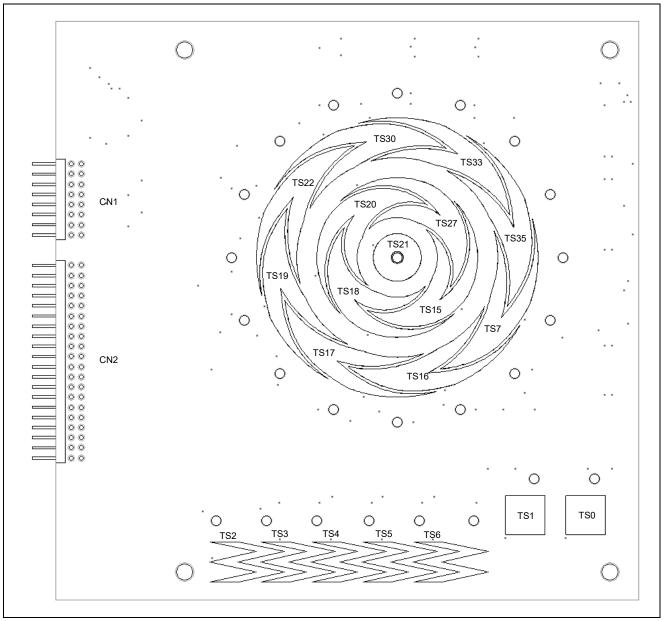


Figure 2.3 Application Board Component Placement (top/component side)



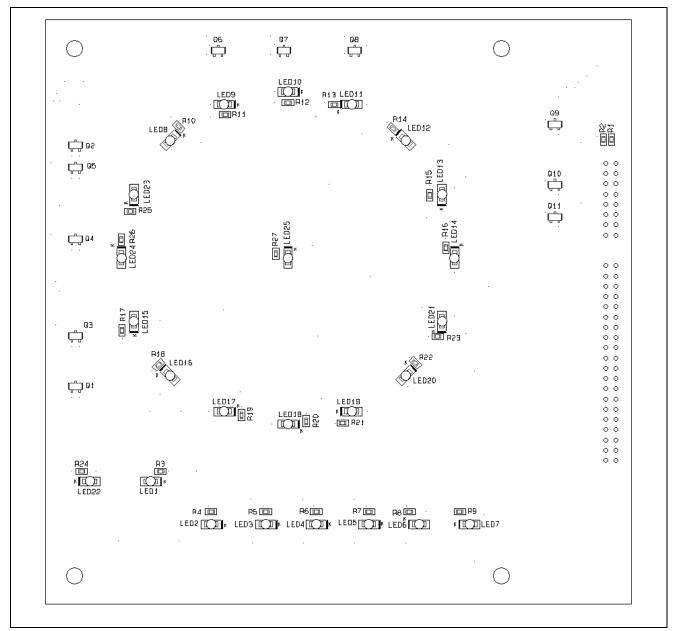


Figure 2.4 Application Board Component Placement (bottom/soldered side)



## 3. Board Attachment & Specifications

## 3.1 Board Connection Configuration

Insert headers CN1 and CN2 on the application board into the corresponding CN1 and CN2 sockets on the CPU board. Make sure both headers are inserted to match the direction and number of pins on the corresponding connectors and that the pins are fully inserted into the sockets.

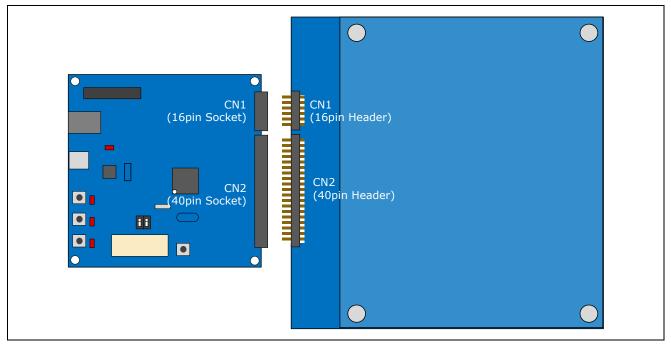


Figure 3.1 Board Connection Direction

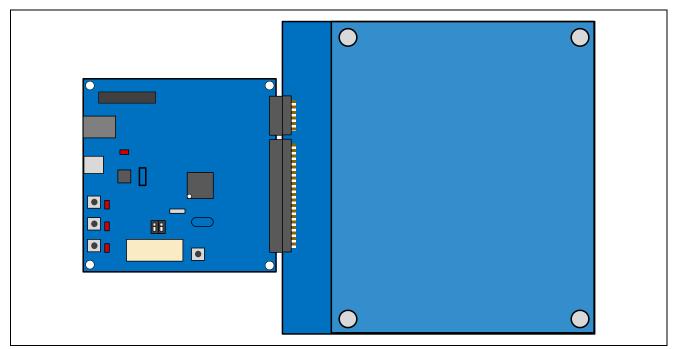


Figure 3.2 Connected Boards



## 4. Headers

Header names (circuit net names) differ for the application board and the CPU board. This section provides details on all headers; the following information can serve as verification tables when using the extension board function.

## 4.1 GPIO Interface

| Table 4.1 | Application Headers | (CN1) |
|-----------|---------------------|-------|
|-----------|---------------------|-------|

| Pin | Header Name | Pin | Header Name |
|-----|-------------|-----|-------------|
| 1   | LED_LOW0    | 2   | LED_LOW 1   |
| 3   | LED_LOW 2   | 4   | LED_LOW 3   |
| 5   | LED_LOW 4   | 6   | LED_LOW 5   |
| 7   | LED_LOW 6   | 8   | -           |
| 9   | LED_COL1    | 10  | LED_COL2    |
| 11  | LED_COL3    | 12  | LED_COL4    |
| 13  | -           | 14  | ADC         |
| 15  | VCC_LED     | 16  | VSS_GND     |

- : Non Connection

## 4.2 CTSU Interface

#### Table 4.2 Application Headers (CN2)

| Pin | Header Name | Pin | Header Name |
|-----|-------------|-----|-------------|
| 1   | TS0         | 2   | TS1         |
| 3   | TS2         | 4   | TS3         |
| 5   | TS4         | 6   | TS5         |
| 7   | TS6         | 8   | TS7         |
| 9   | -           | 10  | -           |
| 11  | -           | 12  | -           |
| 13  | -           | 14  | -           |
| 15  | -           | 16  | TS15        |
| 17  | TS16        | 18  | TS17        |
| 19  | TS18        | 20  | TS19        |
| 21  | TS20        | 22  | TS21        |
| 23  | TS22        | 24  | -           |
| 25  | -           | 26  | -           |
| 27  | -           | 28  | TS27        |
| 29  | -           | 30  | -           |
| 31  | TS30        | 32  | -           |
| 33  | -           | 34  | TS33        |
| 35  | -           | 36  | TS35        |
| 37  | -           | 38  | -           |
| 39  | -           | 40  | -           |

- : Non Connection



## 5. Circuit Diagram

The circuit diagram is shown on the Appendix 1.



## 6. PCB Layout Diagram

The PCB layout diagram is shown on the Appendix 2.



## 7. Parts List

The parts list is shown on the Appendix 3.



## 8. Additional Information

#### **Technical Support**

For more information about how to use the application board, refer to the Renesas website.

For information about the target microcontroller, refer to the corresponding User's Hardware Manual.

For general information on Renesas microcontrollers, visit : <u>https://www.renesas.com/</u>

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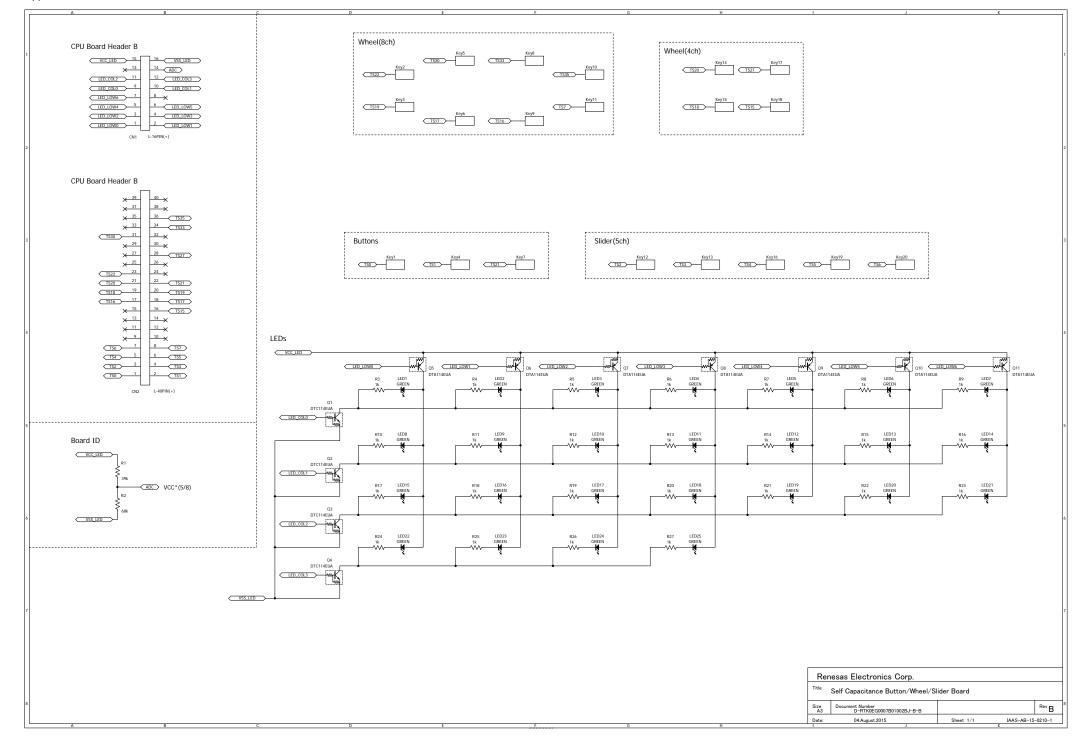
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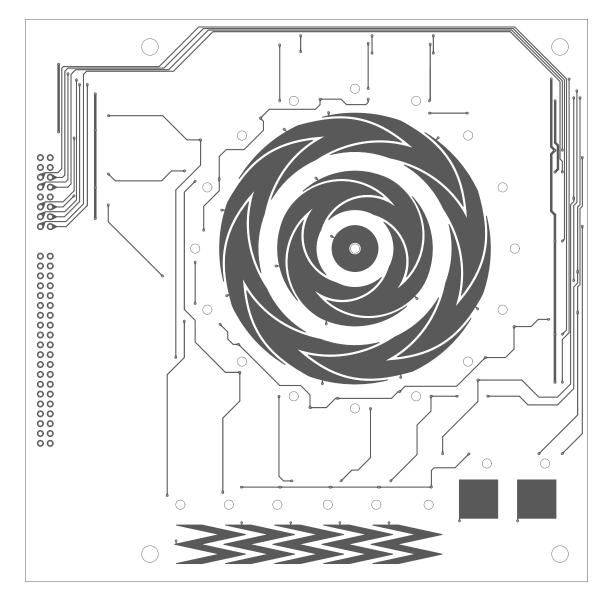
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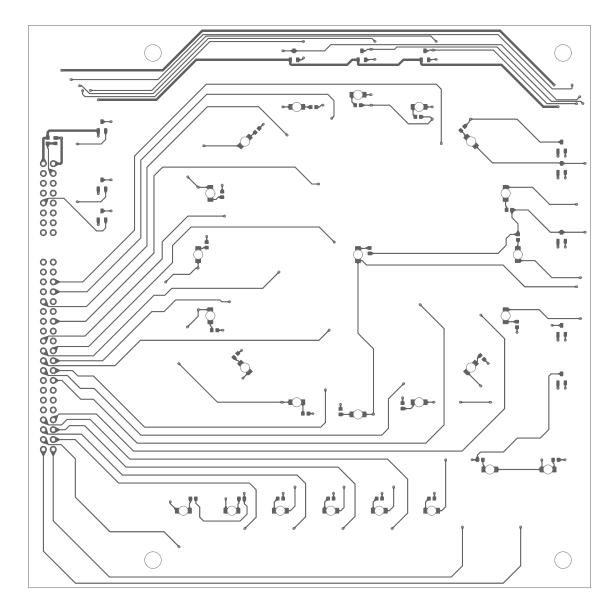


#### Appendix 1.





PCB Top-side Layout



PCB Bottom-side Layout

Appendix 3.

Renesas Electronics Corp.

| 3. |          | PartNo            | RTK0EG000         | 7B01002BJ          | Title  | Self-Capacitano                         | ce Buttons/Wh | neels/  | Slider Board BOM                       |
|----|----------|-------------------|-------------------|--------------------|--------|---|---------------|---------|--|
| No |          | Component<br>Type | Name<br>Reference | Product Number (S  |        | oonent Specification<br>on) Manufacture | Mount/Unmount | Qty/Set | Remarks                                |
| 1  | Right An | gle Pin Header    | CN1               | PSR-420256-08      |        | Hirosugi-Keiki                          | Mount         | 1       | 16-pin(2x8), 2.54mm-pitch              |
| 2  |          | gle Pin Header    | CN2               | PSR-420256-20      |        | Hirosugi-Keiki                          | Mount         | 1       | 40pin(2x20), 2.54mm-pitch              |
| 3  | Chip Res |                   | R1                | MCR03ERTJ393       |        | ROHM                                    | Mount         | 1       | 39k                                    |
| 4  | Chip Res | istor             | R2                | MCR03ERTJ683       |        | ROHM                                    | Mount         | 1       | 68k                                    |
| 5  | Chip Res | istor             | R3-R27            | MCR03ERTJ102       |        | ROHM                                    | Mount         | 25      | 1k                                     |
| 6  | LED      |                   | LED1-LED25        | SML-812MT          |        | ROHM                                    | Mount         | 25      | Green,<br>Reverse-mount available type |
| 7  | Transist | or                | Q1-Q4             | DTC114EKA          |        | ROHM                                    | Mount         | 4       | NPN                                    |
| 8  | Transist | or                | Q5-Q11            | DTA114EKA          |        | ROHM                                    | Mount         | 7       | PNP                                    |
| 9  | Touch El | ectrode           | Key1-20           | -                  |        | -                                       | Mount         | 20      |  |
| 10 | PCB      |                   |                   | RTK0EG0007B01002BJ | REV. A |   | Mount         | 1       |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
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|    |          |                   |                   |                    |        |   |               | ļ       |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
|    |          |                   |                   |                    |        |   |               |         |  |
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|    |          |                   |                   |                    |        |   |               |         | l                                      |

Revision History Self-Capacitance Touch Buttons/Wheels/Slider Board User's Manual

| Rev. | Date         | Description |  |
|------|--------------|-------------|--|
|      |              | Page        |  |
| 1.00 | Feb 17, 2016 |             | First Edition issued                     |
| 1.01 | Apr 26, 2024 | -           | Update Notice and How to Use This Manual |
|      |              | 1           | Added board dimensions                   |
|      |              | 2           | Added regulatory compliance notices      |
|      |              | 12          | Update Additional Information            |

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